



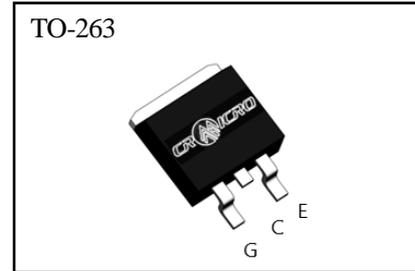
General Description:

Using HUAJING's proprietary trench design and advanced Field Stop (FS) technology, offering superior conduction and switching performances.

V _{CES}	600	V
I _C	8	A
P _{tot} (T _C =25°C)	104	W
V _{CE(sat)}	1.8	V

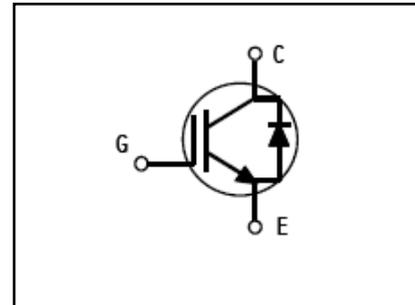
Features:

- FS Trench Technology, Positive temperature coefficient
- Low saturation voltage: V_{CE(sat)}, typ= 1.8V
@ I_C = 8A and T_C = 25 °C
- RoHS Compliant



Applications:

- Motor control
- Home appliances
- General-purpose inverter
- Industrial sewing machine



Package Parameters

Type	Marking	Package	Packing
CRG08T60A03L	G08T60A03L	TO-263	Tape & Reel

Absolute Maximum Ratings (T_j= 25°C unless otherwise specified):

Symbol	Parameter	Rating	Units
V _{CES}	Collector-Emitter Voltage	600	V
V _{GES}	Gate- Emitter Voltage	±20	V
I _C	Collector Current@TC=25°C	16	A
	Collector Current @TC = 100 °C	8	
I _{CM} ^{a1}	Pulsed Collector Current	24	A
I _F	Diode Continuous Forward Current @T _C = 25 °C	20	A
	Diode Continuous Forward Current @T _C = 100 °C	10	A
I _{FM}	Diode Maximum Forward Current	30	A
P _D	Power Dissipation @ T _C = 25 °C	104	W
T _J	Operating Junction	-40~150	°C
T _{stg}	Storage Temperature Range	-55~150	°C
T _L	Maximum Temperature for Soldering	270	°C

^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
R _{θJC}	Thermal Resistance, Junction to case for IGBT	--	1.19	°C/W
R _{θJC}	Thermal Resistance, Junction to case for Diode	--	1.23	°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient	--	43.18	°C/W

Electrical Characteristics of the IGBT (T_j= 25°C unless otherwise specified):

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
OFF Characteristics						
V _{(BR)CES}	Collector-Emitter Breakdown Voltage	V _{GE} =0V, I _{CE} =250μA	600	--	--	V
I _{CES}	Collector-Emitter Leakage Current	V _{GE} =0V, V _{CE} =600V	--	--	1.0	mA
I _{GES(F)}	Gate to Emitter Forward Leakage	V _{GE} =+20V	--	--	+200	nA
I _{GES(R)}	Gate to Source Reverse Leakage	V _{GE} =-20V	--	--	-200	nA
ON Characteristics						
V _{CE(sat)}	Collector-Emitter Saturation Voltage	I _C =8A, V _{GE} =15V	--	1.8	2.4	V
V _{GE(th)}	Gate Threshold Voltage	I _C =250μA, V _{CE} =V _{GE}	4.5	5.6	6.5	V
Pulse width tp≤300μs, δ≤2%						
Dynamic Characteristics						
C _{ies}	Input Capacitance	V _{CE} =25V, V _{GE} =0V f=1MHz	--	611	--	pF
C _{oes}	Output Capacitance		--	63	--	
C _{tes}	Reverse Transfer Capacitance		--	24	--	

Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{CE}=400V, I_C=8A,$ $R_g=10\Omega, V_{GE}=15V,$ Inductive Load, $T_j=25^\circ C,$	--	7	--	ns
t_r	Rise Time		--	23	--	
$t_{d(off)}$	Turn-Off Delay Time		--	48	--	
t_f	Fall Time		--	79	--	
E_{on}	Turn-On Switching Loss	$V_{CE}=480V, I_C=8A,$ $V_{GE}=15V,$	--	0.15	--	mJ
E_{off}	Turn-Off Switching Loss		--	0.17	--	
E_{ts}	Total Switching Loss		--	0.32	--	
Q_g	Total Gate Charge	$V_{CE}=480V, I_C=8A,$ $V_{GE}=15V,$	--	44	--	nC
Electrical Characteristics of the DIODE ($T_j=25^\circ C$ unless otherwise specified):						
V_F	Diode Forward Voltage	$I_F=10A$	--	1.4	2.1	V
t_{rr}	Reverse Recovery Time	$I_F=10A$ $di/dt=100A/\mu S$	--	47	--	ns
I_{rrm}	Reverse Recovery Current		--	7.5	--	A
Q_{rr}	Reverse Recovery Charge		--	176	--	nC

Typical Performance Characteristics

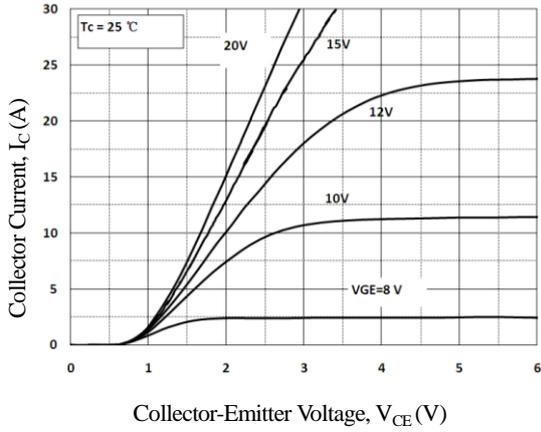


Figure 1. Output Characteristics

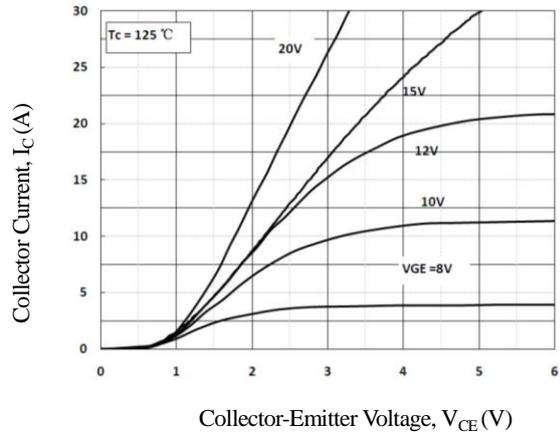


Figure 2. Output Characteristics

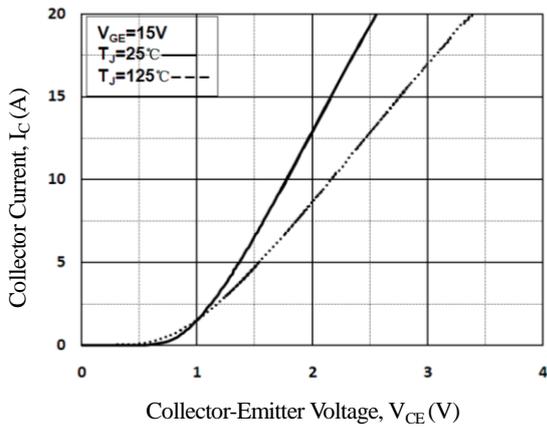


Figure 3. Saturation Voltage Characteristics

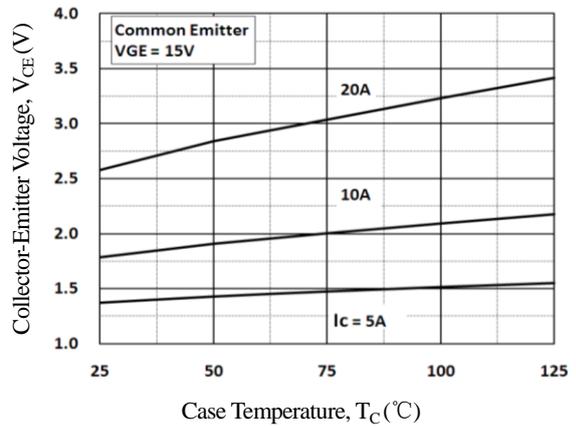


Figure 4. Saturation Voltage - T_c Characteristics

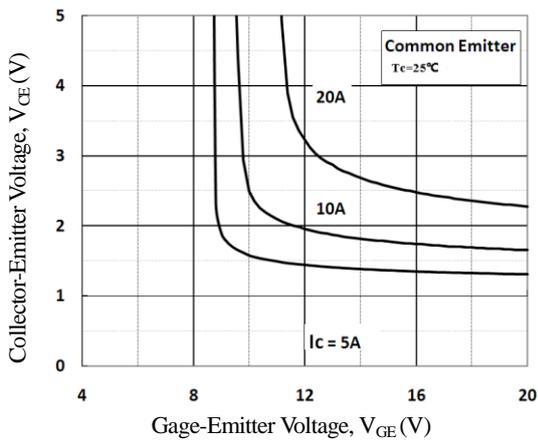


Figure 5. $V_{CE(sat)}$ - V_{GE} Characteristics

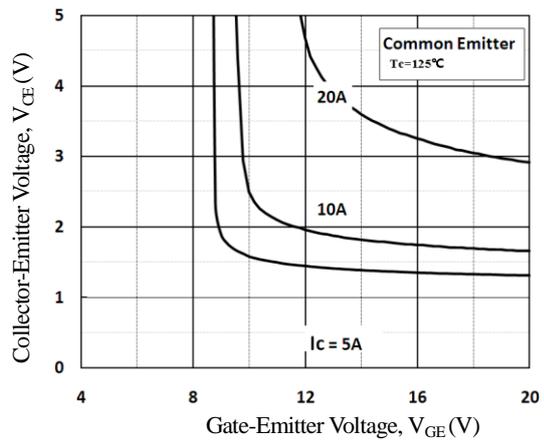


Figure 6. $V_{CE(sat)}$ - V_{GE} Characteristics

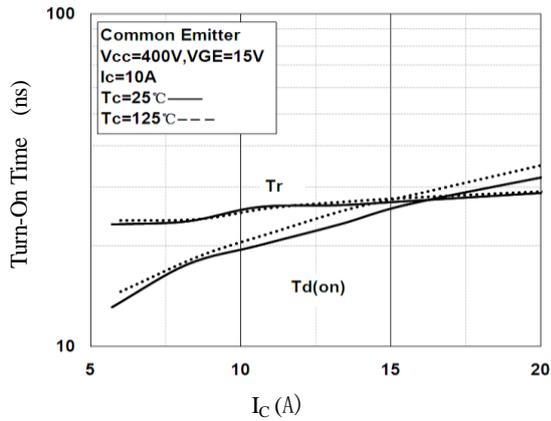


Figure 7. Turn-On Time-Ic Characteristics

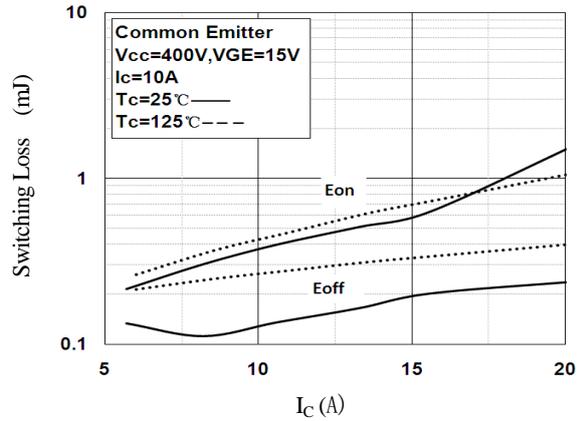


Figure 8. Switching Loss-Ic Characteristics

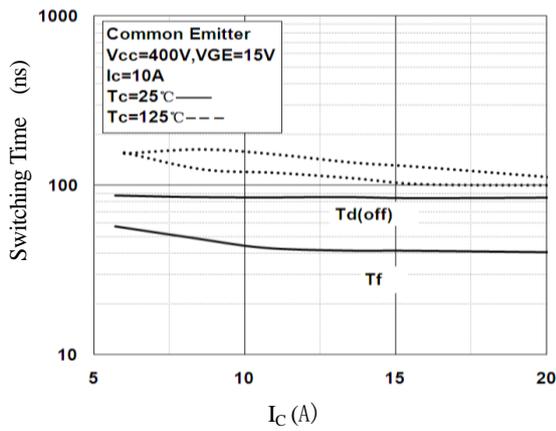


Figure 9. Turn-Off Time-Ic Characteristics

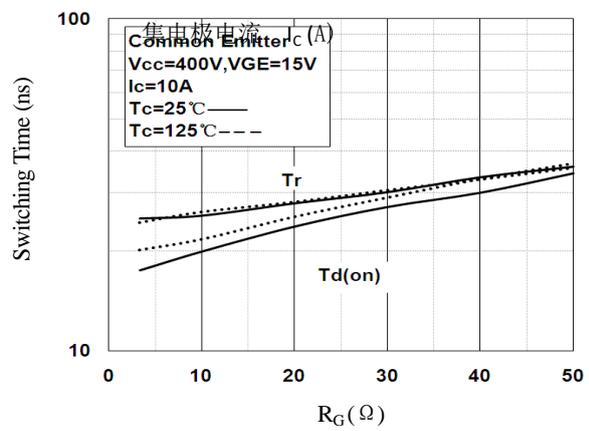


Figure 10. Switching Time- R_G Characteristics

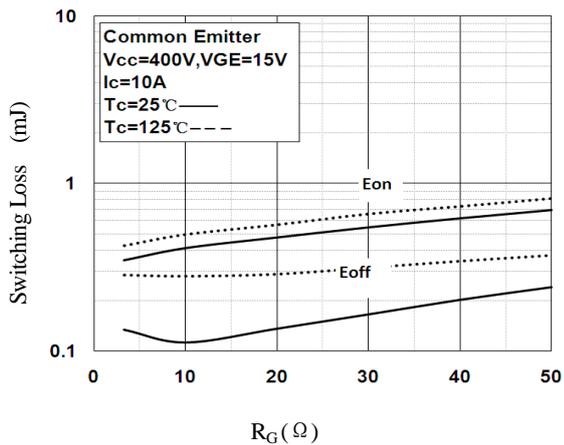


Figure 11. Switching Loss- R_G Characteristics

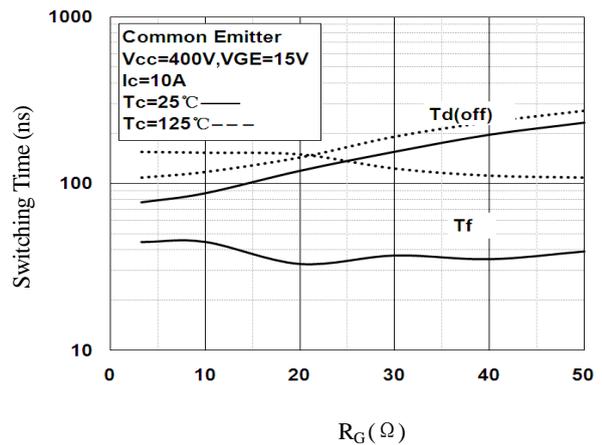


Figure 12. Switching Time- R_G Characteristics

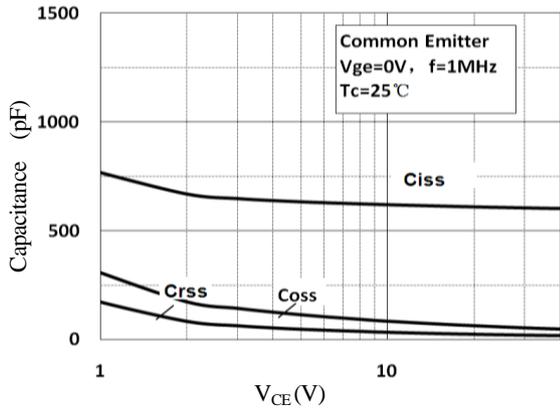


Figure 13. Capacitance Characteristics

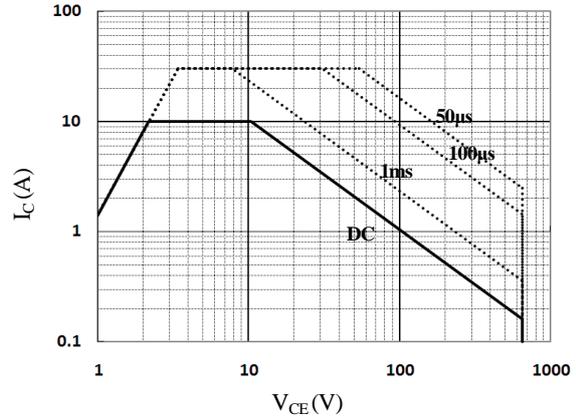


Figure 14. Forward Bias Safe Operating Area

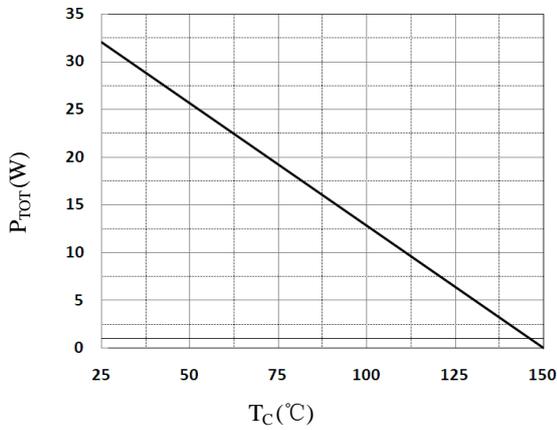


Figure 15. Power Dissipation- T_C Characteristics

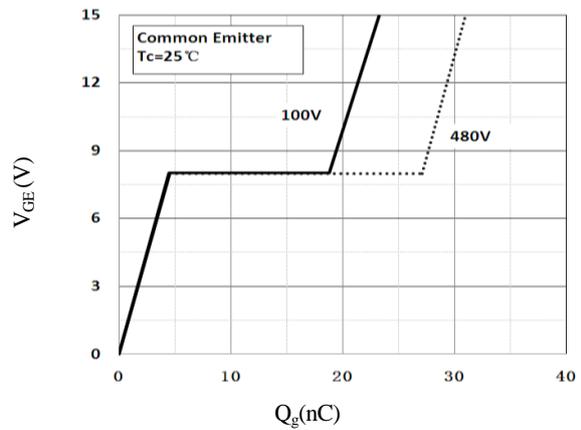


Figure 16. Gage Charge Characteristics

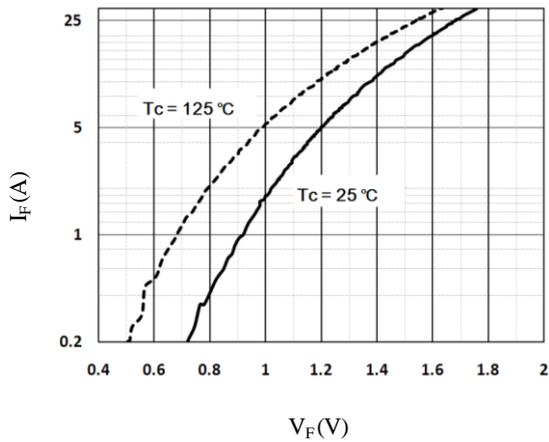


Figure 17. Diode Forward Characteristics

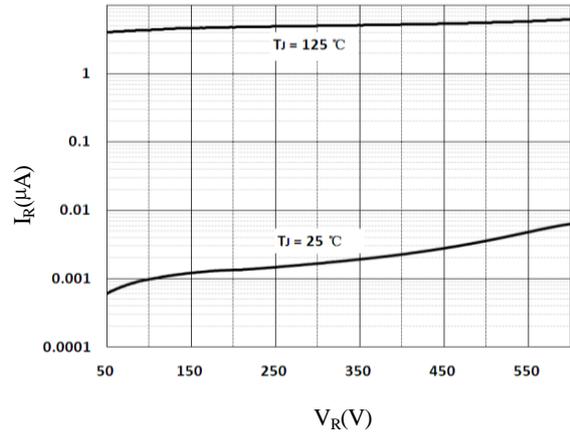


Figure 18. Diode Reverse Characteristics

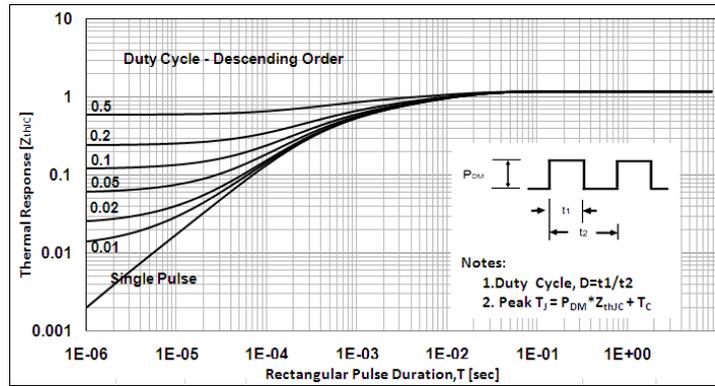
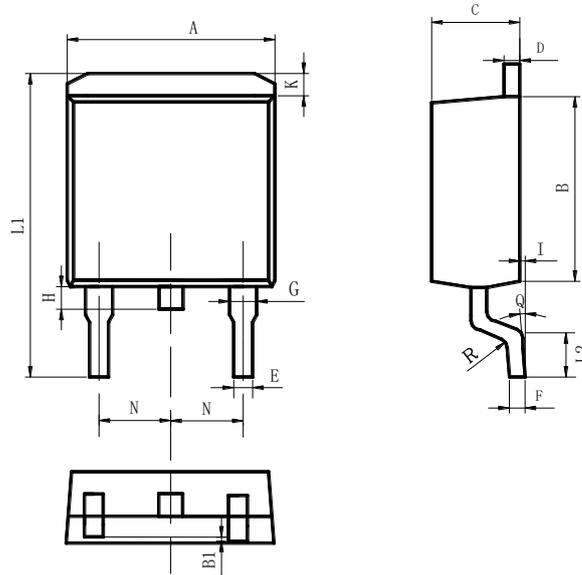


Figure 19.IGBT Transient Thermal Impedance

Package Information:


Items	Values(mm)	
	MIN	MAX
A	9.80	10.40
B	8.90	9.50
B1	0	0.10
C	4.40	4.80
D	1.16	1.37
E	0.70	0.95
F	0.30	0.60
G	1.07	1.47
H	1.30	1.80
K	0.95	1.37
L1	14.50	16.50
L2	1.90	2.90
I	0	0.2
Q	0°	8°
R	0.4	
N	2.39	2.69

TO-263 Package

The name and content of poisonous and harmful material in products

Part's Name	Hazardous Substance									
	Pb	Hg	Cd	Cr (VI)	PBB	PBDE	DIBP	DEHP	DBP	BBP
Limit	≤ 0.1%	≤ 0.1%	≤ 0.01%	≤0.1%	≤ 0.1%	≤0.1%	≤0.1%	≤0.1%	≤0.1%	≤0.1%
Lead Frame	○	○	○	○	○	○	○	○	○	○
Molding	○	○	○	○	○	○	○	○	○	○
Chip	○	○	○	○	○	○	○	○	○	○
Wire Bonding	○	○	○	○	○	○	○	○	○	○
Solder	×	○	○	○	○	○	○	○	○	○
Note	○: Means the hazardous material is under the criterion of 2011/65/EU. ×: Means the hazardous material exceeds the criterion of 2011/65/EU. The plumbum element of solder exist in products presently, but within the allowed range of Eurogroup's RoHS.									

Warnings

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. It is suggested to be used under 80 percent of the maximum ratings of the device.
2. When installing the heat sink, please pay attention to the torsional moment and the smoothness of the heat sink.
3. IGBTs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
4. This publication is made by Huajing Microelectronics and subject to regular change without notice.

WUXI CHINA RESOURCES HUAJING MICROELECTRONICS CO., LTD.

Add: No.14 Liangxi RD. Wuxi, Jiangsu, China **Mail:** 214061 <https://www.crmicro.com>
Tel: 0510-85807228 **Fax:** 0510-85800864

Marketing Part: **Post:** 214061 **Tel / Fax:** 0510-85807228-3663/5508
0510-85800360 (Fax)

Application and Service: **Post:** 214061 **Tel / Fax:** 0510-85807228-3399 / 2227